Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

# 2SK2733

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain-source ON resistance : RDS (ON) = 8.0  $\Omega$  (typ.)

 $\bullet \quad \mbox{High forward transfer admittance} \quad \ \ \, : \, |\, Y_{fs}\,| \, = 0.9 \; S \; (typ.)$ 

• Low leakage current :  $IDSS = 100 \mu A (max) (VDS = 720 V)$ 

• Enhancement-mode :  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

### **Maximum Ratings (Ta = 25°C)**

| Characteristics                              |                | Symbol           | Rating  | Unit  |  |
|--|----------------|------------------|---------|-------|--|
| Drain-source voltage                         |                | $V_{DSS}$        | 900     | V     |  |
| Drain-gate voltage (R <sub>GS</sub> = 20 kΩ) |                | $V_{DGR}$        | 900     | V     |  |
| Gate-source voltage                          |                | V <sub>GSS</sub> | ±30     | V     |  |
| Drain current                                | DC (Note 1)    | I <sub>D</sub>   | 1       | Α     |  |
|  | Pulse (Note 1) | I <sub>DP</sub>  | 3       | A<br> |  |
| Drain power dissipation                      | n (Tc = 25°C)  | P <sub>D</sub>   | 60      | W     |  |
| Single pulse avalanche energy (Note 2)       |                | E <sub>AS</sub>  | 324     | mJ    |  |
| Avalanche current                            |                | I <sub>AR</sub>  | 1       | Α     |  |
| Repetitive avalanche energy (Note 3)         |                | E <sub>AR</sub>  | 6.0     | mJ    |  |
| Channel temperature                          |                | T <sub>ch</sub>  | 150     | °C    |  |
| Storage temperature range                    |                | T <sub>stg</sub> | -55~150 | °C    |  |

# 10.3MAX. 93.6±0.2 1.6MAX. 0.76 1.6MAX. 0.76 1. GATE 2. DRAIN (HEAT SINK) 3. SOURCE JEDEC TO-220AB JEITA SC-46 TOSHIBA 2-10P1B

Weight: 2.0 g (typ.)

### **Thermal Characteristics**

| Characteristics                        | Symbol                 | Max  | Unit |
|--|------------------------|------|------|
| Thermal resistance, channel to case    | R <sub>th (ch-c)</sub> | 2.08 | °C/W |
| Thermal resistance, channel to ambient | R <sub>th (ch-a)</sub> | 83.3 | °C/W |

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 594 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 1 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

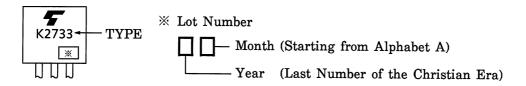
## **Electrical Characteristics (Ta = 25°C)**

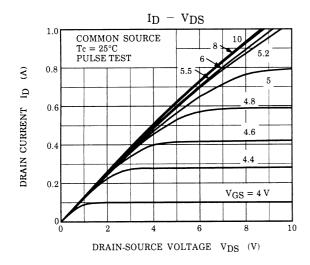
| Charac  | cteristics      | Symbol                | Test Condition   | Min | Тур. | Max | Unit |
|---|-----------------|-----------------------|--|-----|------|-----|------|
| Gate leakage cu                                 | ırrent          | I <sub>GSS</sub>      | V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V   | _   | _    | ±10 | μΑ   |
| Gate-source bro                                 | eakdown voltage | V (BR) GSS            | I <sub>G</sub> = ±10 μA, V <sub>DS</sub> = 0 V   | ±30 | _    | _   | V    |
| Drain cut-off cu                                | rrent           | I <sub>DSS</sub>      | V <sub>DS</sub> = 720 V, V <sub>GS</sub> = 0 V   | _   | _    | 100 | μΑ   |
| Drain-source br                                 | eakdown voltage | V <sub>(BR) DSS</sub> | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V  | 900 | _    | _   | V    |
| Gate threshold v                                | /oltage         | $V_{th}$              | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA  | 2.0 | _    | 4.0 | V    |
| Drain-source O                                  | N resistance    | R <sub>DS</sub> (ON)  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.5 A   | _   | 8.0  | 9.0 | Ω    |
| Forward transfe                                 | r admittance    | Y <sub>fs</sub>       | V <sub>DS</sub> = 20 V, I <sub>D</sub> = 0.5 A   | 0.2 | 0.9  | _   | S    |
| Input capacitano                                | ce              | C <sub>iss</sub>      |  | _   | 370  | _   | pF   |
| Reverse transfe                                 | r capacitance   | C <sub>rss</sub>      | V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz   | _   | 5    | _   |      |
| Output capacitance                              |                 | C <sub>oss</sub>      |  |     | 40   | _   |      |
| Switching time                                  | Rise time       | t <sub>r</sub>        | $V_{GS} = \frac{10 \text{V}}{0 \text{V}} = \frac{I_{D} = 1 \text{A}}{V_{Out}} = \frac{10 \text{V}}{V_{DD}} = \frac{10 \text{V}}{200 \text{V}}$ $\text{Duty} \leq 1\%, \ t_{W} = 10 \text{\mu s}$ | _   | 20   | _   | - ns |
|   | Turn-on time    | t <sub>on</sub>       |  | _   | 70   | _   |      |
|   | Fall time       | t <sub>f</sub>        |  | _   | 30   |     |      |
|   | Turn-off time   | t <sub>off</sub>      |  | _   | 95   | _   |      |
| Total gate charge (gate-source plus gate-drain) |                 | Qg                    |  | _   | 15   | _   |      |
| Gate-source charge                              |                 | $Q_{gs}$              | V <sub>DD</sub> ≈ 400 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1 A  |     | 6    | _   | nC   |
| Gate-drain ("miller") Charge                    |                 | $Q_{gd}$              |  |     | 9    | _   |      |

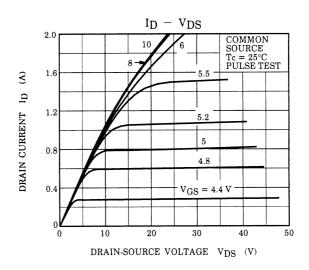
# Source-Drain Ratings and Characteristics (Ta = 25°C)

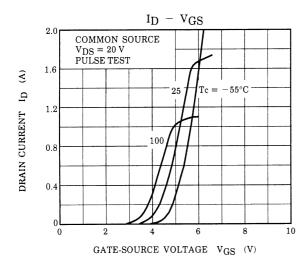
| Characteristics                           | Symbol           | Test Condition                               | Min | Тур. | Max  | Unit |
|---|------------------|--|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I <sub>DR</sub>  | _  | _   | _    | 1    | Α    |
| Pulse drain reverse current (Note 1)      | I <sub>DRP</sub> | _  | _   | _    | 3    | Α    |
| Forward voltage (diode)                   | V <sub>DSF</sub> | I <sub>DR</sub> = 1 A, V <sub>GS</sub> = 0 V | _   | _    | -1.9 | V    |
| Reverse recovery time                     | t <sub>rr</sub>  | I <sub>DR</sub> = 1 A, V <sub>GS</sub> = 0 V | _   | 750  |      | ns   |
| Reverse recovery charge                   | Q <sub>rr</sub>  | dI <sub>DR</sub> / dt = 100 A / μs           | _   | 3    | _    | μC   |

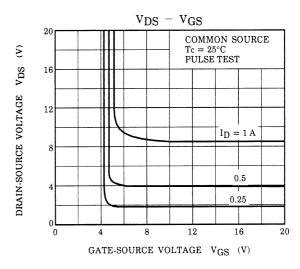
# Marking

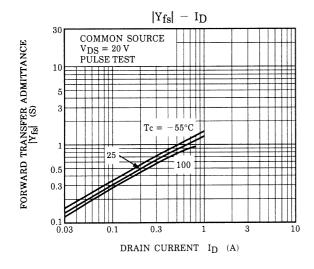


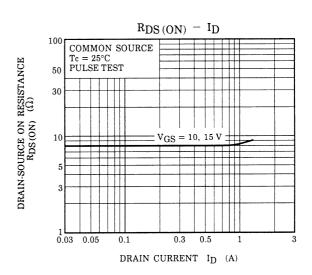




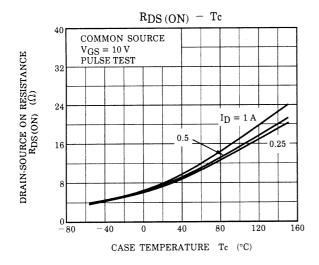


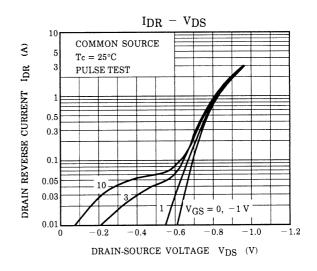


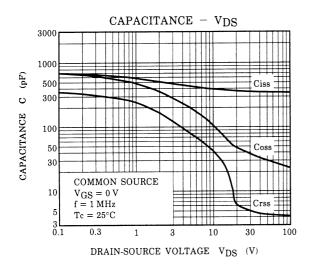


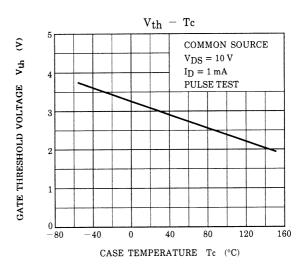


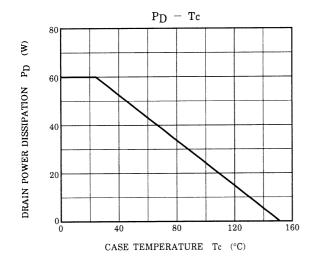
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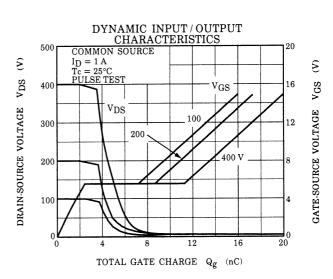


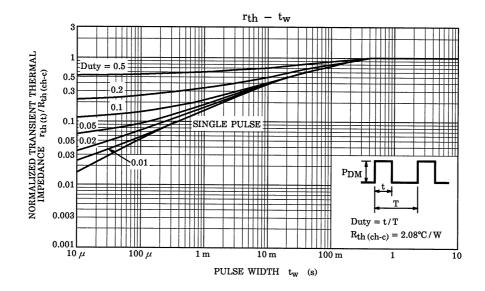


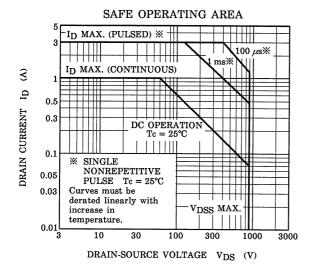


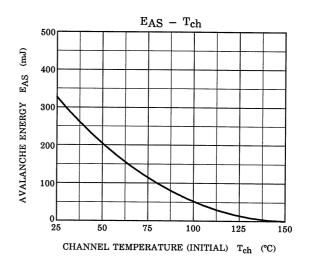


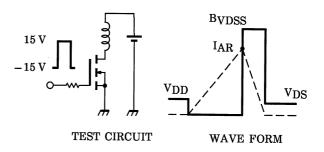












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 594~mH \end{aligned} \qquad EAS &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right) \end{aligned}$$

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